SIEMENS

Data sheet	6ES7590-0BH00-0AA0

SIMATIC S7-1500 / ET 200MP active backplane bus 8 slots for inserting S7-1500 I/O modules for hot swapping for use in the ET 200MP with IM 155-5 PN HF (from FW V4.4.1); S7-1500 mounting rail and slot covers to be ordered separately

Figure similar

General information	
Product type designation	Active Backplane ST 1+8 Slot
HW functional status	from FS01
Firmware version	from V1.0.0
● FW update possible	Yes
Product function	
● I&M data	Yes; I&M0 to I&M3
● Isochronous mode	Yes
● Prioritized startup	Yes
Engineering with	
● STEP 7 TIA Portal configurable/integrated from version	V16 / V17
● STEP 7 configurable/integrated from version	V5.6 and higher
● PROFINET from GSD version/GSD revision	V2.35 / -
Power	
Power available from the backplane bus	2 W
Power loss	
Power loss, typ.	2 W
Hardware configuration	
Slots	
● Grid size	35 mm; Utilization of 25 mm-wide modules possible
● Number of slots	9
— of which for CPU, max.	1; for S7-1500H CPU with CPU firmware V3.1 or higher; interface modules up to V1.1.0 only (active backplane bus)
— of which for IM, max.	1
— of which for PS, max.	8; Max. 2 PS per station
— of which for IO/CM/CP/TM, max.	8
— of which for F-IO, max.	8
● Number of single-width slots, max.	8
Ambient conditions	
Ambient temperature during operation	
● horizontal installation, min.	-30 °C
● horizontal installation, max.	60 °C
● vertical installation, min.	-30 °C
● vertical installation, max.	40 °C
Ambient temperature during storage/transportation	
● min.	-40 °C
● max.	70 °C
Altitude during operation relating to sea level	
● Installation altitude above sea level, max.	5 000 m; Restrictions for installation altitudes > 2 000 m, see manual

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Dimensions	
Width	294 mm
Height	99 mm
Depth	14 mm

Weights	
Weight, approx.	246 g

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